

Latent Claims

1 1. Method for producing of circuit arrangements, the
2 components of which are attached to the top surface (12) of
3 a carrier body (5) having thermal through contacts (7),
4 wherein the thermal through contacts (7) are closed from
5 the underside (13) of the carrier body (5) with screen
6 printing material (8) by a screen printing process prior to
7 the soldering operation,
8 characterized in that
9 the screen printing process is performed following the
10 application of a first metallizing layer (6) to the carrier
11 body (5), said metallizing layer forming a first base
12 metallization,
13 and that, following the curing of the screen printing
14 material (8), remainders of the screen printing material
15 (8) protruding from the underside of the carrier body (5)
16 are removed by at least one mechanical cleaning process
17 and/or by a chemical cleaning process.

1 2. Method of claim 1, characterized in that mechanical brush
2 grinding is used as said mechanical cleaning operation.

1 3. Method of claim 1 or 2, characterized in that, following at
2 least one cleaning process, a metallizing layer (17)
3 forming the final metallization is applied to the base
4 metallization (6).

1 4. Method of one of the claims 1 to 3, characterized in that
2 following the application of the metallization layer (17)

3 forming the final metallization, the components of the
4 circuit arrangement are attached to the top surface (12) of
5 the carrier body (5) by a reflow soldering process.

1 5. Method of one of the claims 1 to 4, characterized in that
2 a thermally conducting, electrically insulating film (9) is
3 applied to the underside (13) of the carrier body (5).

1 6. Method of one of claims 1 to 5, characterized in that the
2 thermally conducting, electrically insulating film (9) is
3 connected to a cooling body (10).